

- NOTES:
1. Dimensions are in mm unless specified otherwise. Tolerances are as indicated on Dimensions layer unless otherwise noted.
 2. All dimensional limits apply after plating or processing.
 3. Refer to drill table for hole size tolerances.
 4. Hole / slot plating to be 0.001" minimum average and 0.0008" absolute minimum.
 5. Hole / slot diameters are specified after plating.
 6. Thickness and tolerances for flex circuit and stiffeners are as indicated on Layer Stack detail.
 7. Base Materials: As noted in layer stack.
 8. Coverlay: As noted in layer stack. Registration to be within +/- 0.003 of respective signal layers.
 9. Silkscreen: White non-conductive ink (top and bottom). No ink to appear on exposed copper.
 10. Finish: Electroless Nickel Immersion Gold (ENIG). Finish both sides with 150 micro inches minimum electroless Nickel (Ni) followed by minimum 2 microinches immersion Gold (Au).
 11. Electrical Test: Perform 100% continuity and isolation testing per current IPC test methods.
 12. Controlled Impedance is not required.
 13. Do not panelize. Supply as individual flexible PCBs.

The FPC is single layer with all the components and traces on the Base Copper layer and the PI stiffeners on the bottom

Polyimide	25 um
Coverlay Adhesive	35 um
Base Copper	36 um
Adhesive	36 um
Polyimide	25 um

25 um

FINISHED THICKNESS
121 um +/- 10 um

Flex Circuit

Polyimide

0.15 mm +/- 0.05 mm

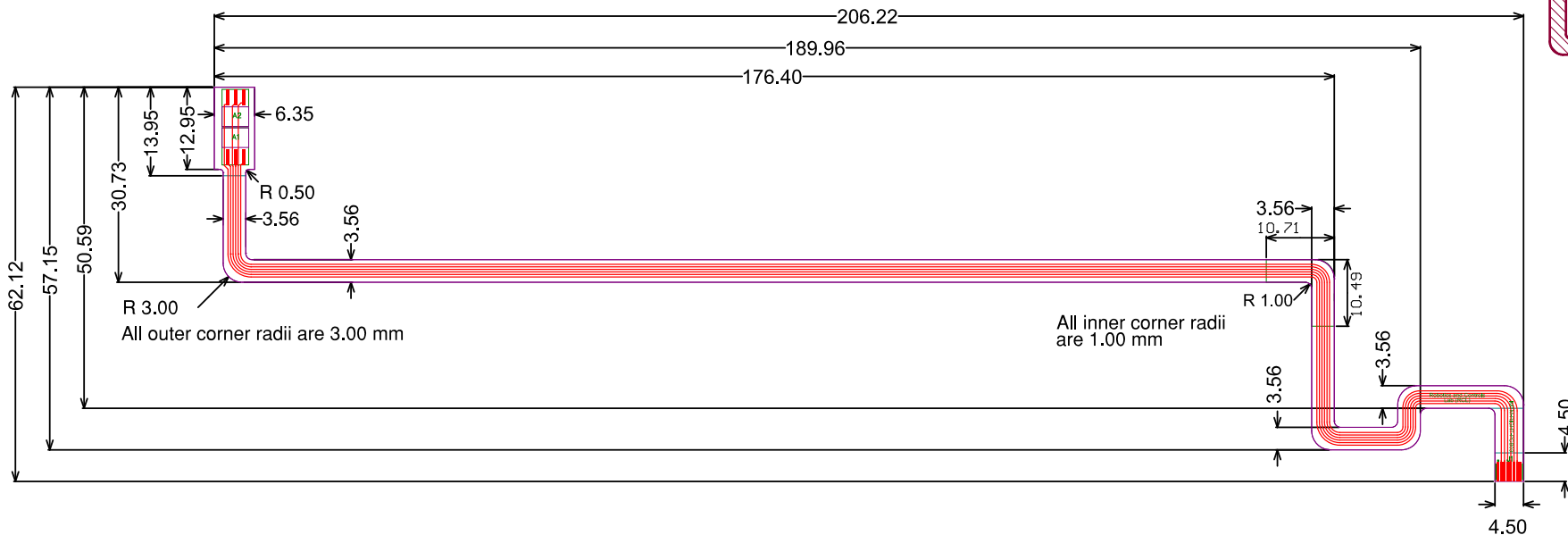
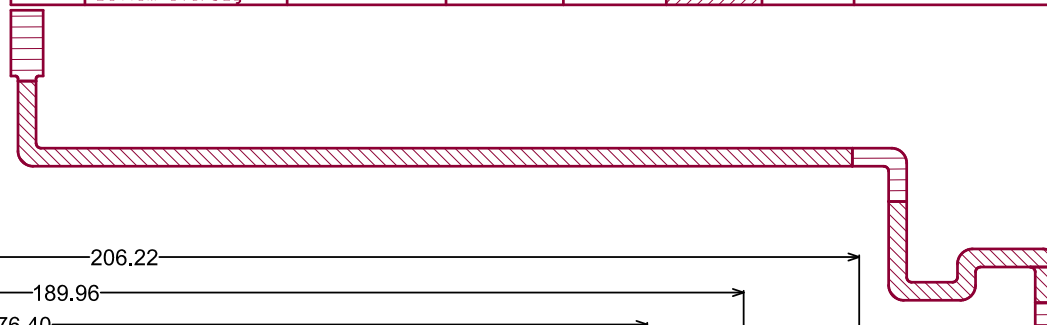
0.27 mm +/- 0.05 mm

FINISHED THICKNESS

Flex Layer Stack Detail
NOT TO SCALE

Polyimide Stiffener Detail
NOT TO SCALE

Layer	Name	Material	Thickness	Constant	Generic	Flex	Polymide Stiffener
	Flex Top Overlay						
	Flex Top Coverlay	PI + Adhesive	0.050mm	3.4			
1	Top Layer	Copper	0.036mm				
	Polyimide	Adhesive + PI	0.025mm	3.4			
2	Bottom Layer	Copper	0.036mm				
	Bottom Coverlay	PI + Adhesive	0.050mm	3.4			
	Bottom Overlay						



Tolerances unless otherwise specified:

.X +/- 0.20
.XX +/- 0.10
.XXX +/- 0.05

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V6J 1R6

ENGINEER:
Amir H. Hadi 2020.08.12
PCB DESIGNER:
Amir H. Hadi 2020.08.12
DATE:
7/19/2021
FILE NAME:
IMTM-Right-PCB03.PcbDoc

TITLE:
Instrumented MTM
HLE Flex Interconnect

PART NO.:
IMTM-RIGHT-PCB03

DWG NO.:
IMTM-RIGHT-PCB03

REV:
A

SCALE:
1:1